12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20250115001.1
Qualification of RFAB using qualified Process Technology, Die Revision, & BOM options for select devices
Change Notification / Sample Request

Date: January 17, 2025
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) process.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200-mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

Change Management Team
SC Business Services

20250115001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
NE556N	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250115001.1	PCN Date:	January 17, 2025
Title:	Qualification of RFAB using qualified Process Technology, Die Revision, & BOM options for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	April 17, 2025	Sample requests accepted until:	March 18, 2025

***Sample requests received after March 18, 2025 will not be supported.**

Change Type:

☐	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the TIB qualified process technology and & BOM options for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
SH-BIP-1	JI1	150 mm	RFAB	TIB	300 mm

The die was also changed as a result of the process change.

Construction differences are as follows:

Group 1 BOM Table (RFAB/Process migration, die change plus BOM update (PDIP Devices)):

	Current	Additional
Bond wire composition, diameter	Cu, 0.96	Cu, 0.8 mil

Group 2 BOM Table (RFAB/Process migration, die change plus BOM update (SOIC Device)):

	Current	Additional
Bond wire composition, diameter	Cu, 0.96 mil	Cu, 0.8 mil
Pin one identifier	Stripe or Dot	Dot

Datasheet updates are noted below:

Changes from Revision G (June 2006) to Revision H (December 2024) **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document ... 1
- Added *Pin Configuration and Functions*, *Specifications*, *Detailed Description*, *Application and Implementation*, *Device and Documentation Support* sections and associated subsections ... 1
- Updated *Description*, *Applications*, and *Features* sections ... 1
- Added DB package to data sheet ... 1
- Deleted package thermal information and related footnotes from *Absolute Maximum Ratings* ... 3
- Added *ESD Ratings* table and HBM and CDM specifications ... 3
- Deleted redundant input voltage (V_I) specification in *Recommended Operating Conditions* ... 3
- Changed *Power Dissipation Ratings* table to *Thermal Information*, and updated per-package thermal specifications ... 3
- Changed *Operating Characteristics* title to *Switching Characteristics*, and clarified that values are specified by design or characterization and are not production tested ... 6
- Deleted initial error of timing interval specification in *Switching Characteristics* and clarified that output rise and fall times are 20% to 80% and 80% to 20%, respectively ... 6

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
Nx556, Sx556	SLFS023G	**SLFS023H**	http://www.ti.com/product/NA556

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	New
Die Rev [2P]	**Die Rev [2P]**
B	**A**

Sample product shipping label (not actual product label):

Product Affected:

Group 1 Device List (RFAB/Process migration, die change plus BOM update (PDIP Device)):

NE556N

Group 2 Device list(RFAB/Process migration, die change plus BOM update (SOIC Devices)):

NA556DR	NE556DR

For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: NE556DR	QBS Process/Package Reference: LM2901BQDRQ1	QBS Process/Package Reference: MC33063ADR	QBS Process Reference: MC33063ADR	QBS Package Reference: OPA4992QDRQ1	QBS Package Reference: LM2901QDRQ1
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-	-	1/77/0	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	1/77/0	3/231/0	3/231/0	-	1/77/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	1/77/0	3/231/0	3/231/0	1/77/0	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	1/77/0	3/231/0	3/231/0	1/77/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	1/77/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	1/77/0	-	-	1/77/0	1/77/0

Type	#	Test Name	Condition	Duration	Qual Device: NE556DR	QBS Process/Package Reference: LM2901BQDRQ1	QBS Process/Package Reference: MC33063ADR	QBS Process Reference: MC33063ADR	QBS Package Reference: OPA4992QDRQ1	QBS Package Reference: LM2901QDRQ1
HTOL	B1	Life Test	125C	1000 Hours	-	-	2/154/0	1/77/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	1/77/0	-	-	1/77/0	1/77/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	1/800/0	2/1600/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	1/10/0	-	-	1/10/0	1/10/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	1/3/0	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	1/3/0	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	1/3/0	-	1/6/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0

- QBS: Qual By Similarity
- Qual Device NE556DR is qualified at MSL1 260C
  - Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
  - The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
  - The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
  - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2308-038

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: NE556N	QBS Package Reference: NE5532P	QBS Package Reference: TS12A4514P	QBS Package Reference: UCC37322P	QBS Process Reference: MC33063ADR	QBS Process Reference: MC33063ADR	QBS Package Reference: SN74HC00N	QBS Package Reference: SN74HC04N	QBS Package Reference: SN74HC164N
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	-	3/231/0	3/231/0	1/77/0	1/77/0	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	1/77/0	3/231/0	-	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	-	-	-	3/231/0	3/231/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	1/77/0	3/231/0	3/231/0	3/231/0	1/77/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	1/77/0	-	1/77/0	3/231/0	3/231/0	3/231/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	2/154/0	1/77/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	1/800/0	2/1600/0	-	-	-
SD	C3	PB-Free Solderability	8 Hours Steam Age	-	-	3/66/0	-	3/66/0	-	-	-	-	-
ESD	E2	ESD CDM	-	2000 Volts	-	-	-	-	-	-	1/3/0	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-	1/3/0	-	-	-	-

Type	#	Test Name	Condition	Duration	Qual Device: NE556N	QBS Package Reference: NE5532P	QBS Package Reference: TS12A4514P	QBS Package Reference: UCC37322P	QBS Process Reference: MC33063ADR	QBS Process Reference: MC33063ADR	QBS Package Reference: SN74HC00N	QBS Package Reference: SN74HC04N	QBS Package Reference: SN74HC164N
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	1/3/0	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	1/3/0	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	1/30/0	1/30/0	-	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device NE556N is qualified at NOT CLASSIFIED NOT CLASSIFIED

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2308-039

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.